

Product Change Notice

Issue Date: December 4, 2018

Change Type:



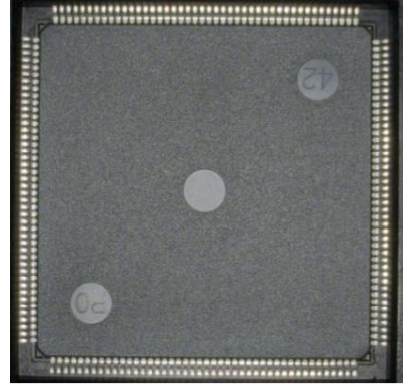

Assembly site change from Epson Singapore to ASE-ChungLi Taiwan for PCI9030-AA60PI F.
 Assembly BOM change for PCI9054-AC50PI F and PCI9030-AA60PI F.

Parts Affected:

PCI9054-AC50PI F
 PCI9030-AA60PI F

Description and Extent of Change:

Assembly BOM changes:

Item	Current	New
Mold Compound	CV8000 series	EME-G600 series
Physical Appearance	Top	Top
		
	Bottom	Bottom
	 <p style="text-align: center;">(PCI9030-AA60PI F)</p>	 <p style="text-align: center;">(PCI9030-AA60PI F)</p>

Reasons for Change:

The current Epson Singapore assembly site has capacity limitations to meet order demand. Moving the assembly site to ASE ChungLi Taiwan with standardized QFP-176 pin assembly BOM to improve assembly capacity and assembly lead time.



Effect of Change on Fit, Form, Function, Quality, or Reliability:

Form, fit, function, quality and reliability of the products will not be affected by the proposed change. Each device specification will remain the same, which will ensure product electrical performance remains the same.

Effective Date of Change:

Current products last order by March-31st, 2019. Product using this change will begin after April-1st, 2019. Timing of shipment of the changed part will vary by part number depending on customer demand, and inventory levels.

Qualification Data:

- 1) Qualification data has been generated and approved.
- 2) Qualification Data is attached.

Test vehicle:	Q21	PCI9054-AC50PI F	PCI9030-AA60PI F
Die size (mm):	7.46 x 7.46	5.78 x 5.78	4.95 x 4.95
Die Technology:	0.35um (Epson)	0.35um (Epson)	0.35um (Epson)
Assembly Site:	ASECL, Taiwan	ASECL, Taiwan	ASECL, Taiwan
Package:	176pin, QFP 24x24x1.4mm3	176pin, QFP 24x24x1.4mm3	176pin, QFP 24x24x1.4mm3
Leadframe Material:	Cu Alloy Etched	Cu Alloy Etched	Cu Alloy Etched
Die Attach:	EN-4000 series	EN-4000 series	EN-4000 series
Wire Size/Type:	0.8mil, 4N Au	0.8mil, 4N Au	0.8mil, 4N Au
Mold Compound:	EME-G600 series	EME-G600 series	EME-G600 series
Lead Finish:	matte-Sn	matte-Sn	matte-Sn
Temperature Humidity Bias 85C/85%RH, Vmax, 1000hr w/ MSL3 Preconditioning	0/135 (3 lots)	Reference	Reference
High Temperature Storage Ta=150C, 1000hr w/ MSL3 Preconditioning	0/135 (3 lots)		
Temperature Cycling -65/+150C, 500cyc w/ MSL3 Preconditioning	0/135 (3 lots)		
Autoclave 121C/100%RH, 200hr w/ MSL3 Preconditioning	0/135 (3 lots)		

Please contact your Broadcom Inc. field sales engineer or Contact Center for any questions or support requirements. Please return any response as soon as possible, but not to exceed 30 days.